

ABSTRACT OF THE DISCLOSURE

Multilayer test probe structures are electrochemically fabricated via depositions of one or more materials in a plurality of overlaying and adhered layers. In some embodiments each probe structure may include a plurality of contact arms or contact tips that are used for contacting a specific pad or plurality of pads wherein the arms and/or tips are configured in such away so as to provide a scrubbing motion (e.g. a motion perpendicular to a primary relative movement motion between a probe carrier and the IC) as the probe element or array is made to contact an IC, or the like, and particularly when the motion between the probe or probes and the IC occurs primarily in a direction that is perpendicular to a plane of a surface of the IC. In some embodiments arrays of multiple probes are provided and even formed in desired relative position simultaneously.